



RAYSTAR

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RX240128A-FGN

SPECIFICATION

CUSTOMER:

APPROVED BY	
PCB VERSION	
DATE	

FOR CUSTOMER USE ONLY

SALES BY	APPROVED BY	CHECKED BY	PREPARED BY

ISSUED DATE:

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1. Revision History

DATE	VERSION	REVISED PAGE NO.	Note
2012/06/25	1		First issue

RAYSTAR OPTRONICS

2. General Specification

The Features of the Module is description as follow:

- Module dimension: 96.0 x 65.0 x 2.9 (max.) mm³
- View area: 92.0 x 53.0 mm²
- Active area: 83.975 x 44.775mm²
- Number of Dots: 240 x 128
- Dot size: 0.325 x 0.325 mm²
- Dot pitch: 0.35 x 0.35 mm²
- LCD type: FSTN Positive, Reflective,
- Duty: 1/128
- View direction: 6 o'clock
- Backlight Type: Without backlight

3. Module Coding System

R	X	240128	A	-	F	G	N
1	2	3	4	-	5	6	7

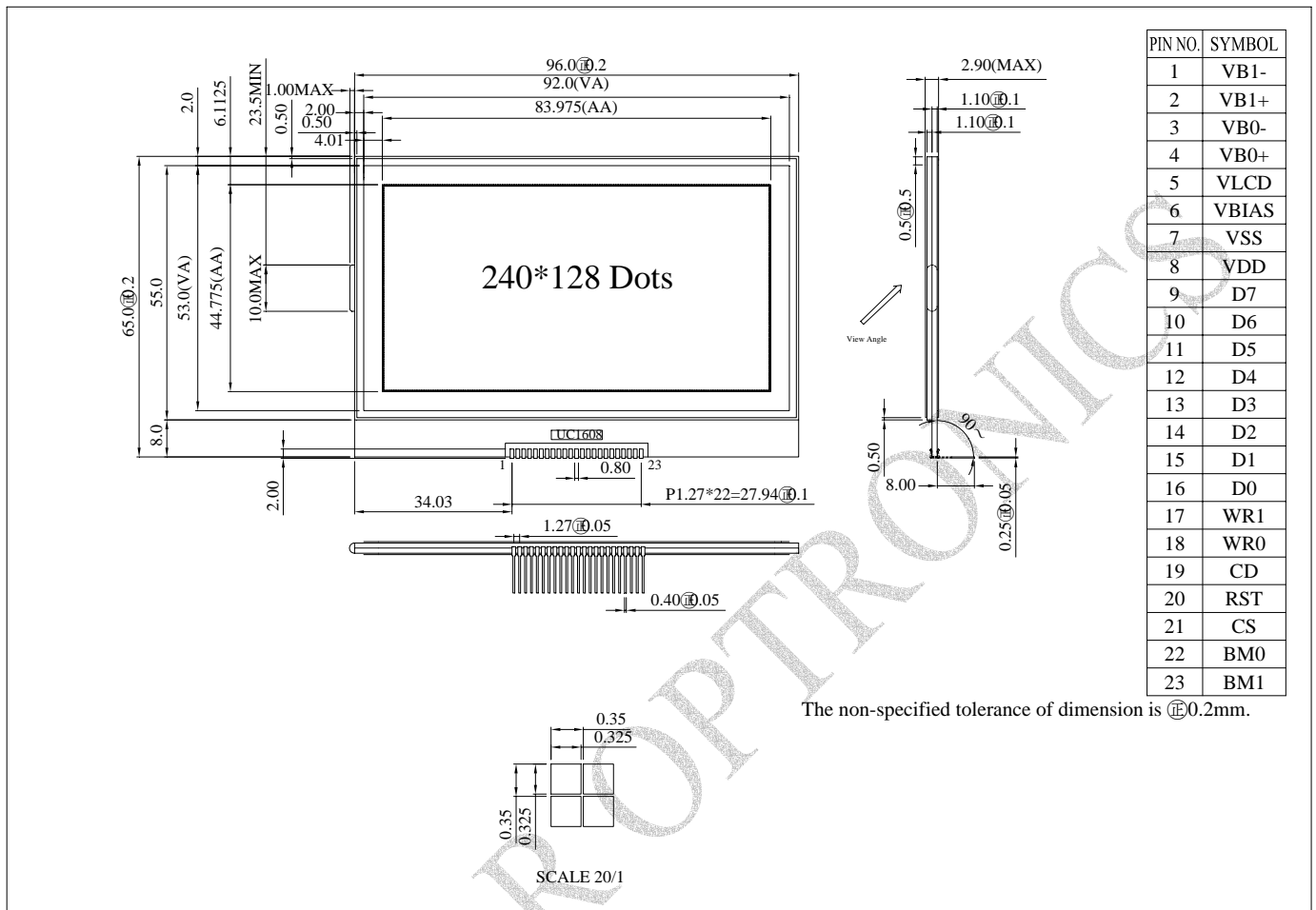
Item	Description		
1	R : Raystar Optronics Inc.		
2	Display Type: COG		
3	Number of dots : 240 x128 Dots		
4	Serials code		
5	LCD	P : TN Positive, Gray	
		N : TN Negative,	
		G : STN Positive, Gray	
		Y : STN Positive, Yellow Green	
		B : STN Negative, Blue	
		F : FSTN Positive	
		T : FSTN Negative	
6	Polarizer Type, Temperature range, View direction	A : Reflective, N.T, 6:00	K : Transflective, W.T,12:00
		D : Reflective, N.T, 12:00	1 : Transflective, U.T,6:00
		G : Reflective, W. T, 6:00	4 : Transflective, U.T.12:00
		J : Reflective, W. T, 12:00	C : Transmissive, N.T,6:00
		0 : Reflective, U. T, 6:00	F : Transmissive, N.T,12:00
		3 : Reflective, U. T, 12:00	I : Transmissive, W. T, 6:00
		B : Transflective, N.T,6:00	L : Transmissive, W.T,12:00
		E : Transflective, N.T.12:00	2 : Transmissive, U. T, 6:00
		H : Transflective, W.T,6:00	5 : Transmissive, U.T,12:00
7	Backlight	N : Without backlight	Y : LED, Yellow Green
		P : EL, Blue green	A : LED, Amber
		T : EL, Green	W : LED, White
		D : EL, White	O : LED, Orange
		F : CCFL, White	G : LED, Green

4. Interface Pin Function

Pin No.	Symbol	Type	Description																																													
1	VB1-	PWR	LCD Bias Voltages. These are the voltage source to provide SEG driving currents. These voltages are generated internally. Connect capacitors of CBX between VBX+ and VBX-. The resistance of these four traces directly affects the SEG driving strength of the resulting LCD module. Minimize the trace resistance is critical in achieving high quality image.																																													
2	VB1+																																															
3	VB0-																																															
4	VB0+																																															
5	V _{LCD}	PWR	Main LCD Power Supply. Connect these pins together.																																													
6	V _{BIAS}	I	This is the reference voltage to generate the actual SEG driving voltage. VBIAS can be used to fine tune VLCD by external variable resistors. Internal resistor network has been provided to simplify external trimming circuit. In COF application, connect a small bypass capacitor between VBIAS and VSS to reduce noise.																																													
7	V _{SS}	PWR	Ground																																													
8	V _{DD}	PWR	Supply Voltage for logic																																													
9	D7	I/O	Bi-directional bus for both serial and parallel host interfaces. In serial modes, connect D[0] to SCK, D[3] to SDA,																																													
10	D6																																															
11	D5																																															
12	D4																																															
13	D3																																															
14	D2																																															
15	D1																																															
16	D0																																															
			<table border="1"> <thead> <tr> <th></th> <th>BM=1x (Parallel)</th> <th>BM=0x (Parallel)</th> <th>BM=01 (S9)</th> <th>BM=00 (S8/S8uc)</th> </tr> </thead> <tbody> <tr> <td>D0</td> <td>D0</td> <td>D0/D4</td> <td>SCK</td> <td>SCK</td> </tr> <tr> <td>D1</td> <td>D1</td> <td>D1/D5</td> <td>-</td> <td>-</td> </tr> <tr> <td>D2</td> <td>D2</td> <td>D2/D6</td> <td>-</td> <td>-</td> </tr> <tr> <td>D3</td> <td>D3</td> <td>D3/D7</td> <td>SDA</td> <td>SDA</td> </tr> <tr> <td>D4</td> <td>D4</td> <td>-</td> <td>-</td> <td>-</td> </tr> <tr> <td>D5</td> <td>D5</td> <td>-</td> <td>-</td> <td>-</td> </tr> <tr> <td>D6</td> <td>D6</td> <td>-</td> <td>S9</td> <td>S8/S8uc</td> </tr> <tr> <td>D7</td> <td>D7</td> <td>0</td> <td>1</td> <td>1</td> </tr> </tbody> </table>		BM=1x (Parallel)	BM=0x (Parallel)	BM=01 (S9)	BM=00 (S8/S8uc)	D0	D0	D0/D4	SCK	SCK	D1	D1	D1/D5	-	-	D2	D2	D2/D6	-	-	D3	D3	D3/D7	SDA	SDA	D4	D4	-	-	-	D5	D5	-	-	-	D6	D6	-	S9	S8/S8uc	D7	D7	0	1	1
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D6	D6	-	S9	S8/S8uc																																												
D7	D7	0	1	1																																												
			Connect unused pins to VDD or VSS.																																													
17	WR1	I	WR[1:0] controls the read/write operation of the host interface. See Host Interface section for more detail. In parallel mode, WR[1:0] meaning depends on whether the interface is in the 6800 mode or the 8080 mode. In serial interface modes, these two pins are not used, connect them to VSS.																																													
18	WR0																																															
19	CD	I	Select Control data or Display data for read/write operation. In S9 mode, CD pin is not used. Connect CD to VSS when not used. "L": Control data "H": Display data																																													

20	RST	I	<p>When RST="L", all control registers are re-initialized by their default states.</p> <p>Since UC1608x has built-in Power-ON-Reset and Software Reset command, RST pin is not required for proper chip operation. When RST is not used, connect the pin to VDD.</p>																								
21	CS	I	<p>Chip Select. The chip is selected when CS="H". When the chip is not selected, D[7:0] will be high impedance.</p>																								
22	BM0	I	<p>Bus mode: The interface bus mode is determined by BM[1:0] and D[7:6] by the following relationship:</p> <table border="1" data-bbox="592 589 1337 967"> <thead> <tr> <th>BM[1:0]</th> <th>D[7:6]</th> <th>Mode</th> </tr> </thead> <tbody> <tr> <td>11</td> <td>Data</td> <td>6800/8-bit</td> </tr> <tr> <td>10</td> <td>Data</td> <td>8080/8-bit</td> </tr> <tr> <td>01</td> <td>0X</td> <td>6800/4-bit</td> </tr> <tr> <td>00</td> <td>0X</td> <td>8080/4-bit</td> </tr> <tr> <td>01</td> <td>10</td> <td>3-wire SPI w/ 9-bit token (S9: conventional)</td> </tr> <tr> <td>00</td> <td>10</td> <td>4-wire SPI w/ 8-bit token (S8: conventional)</td> </tr> <tr> <td>00</td> <td>11</td> <td>3- or 4-wire SPI w/ 8-bit token (S8uc: Ultra-Compact)</td> </tr> </tbody> </table>	BM[1:0]	D[7:6]	Mode	11	Data	6800/8-bit	10	Data	8080/8-bit	01	0X	6800/4-bit	00	0X	8080/4-bit	01	10	3-wire SPI w/ 9-bit token (S9: conventional)	00	10	4-wire SPI w/ 8-bit token (S8: conventional)	00	11	3- or 4-wire SPI w/ 8-bit token (S8uc: Ultra-Compact)
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23	BM1																										

5. Outline Dimension & Block Diagram



6. Display Command

The following is a list of host commands support by UC1608

C/D: 0: Control, 1: Data

W/R: 0: Write Cycle, 1: Read Cycle

Useful Data bits

– Don't Care



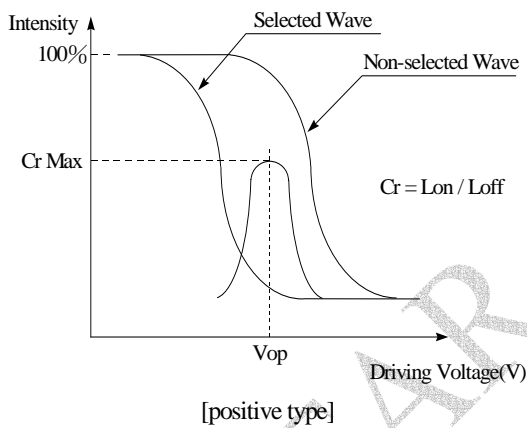
Command	C/D	W/R	D7	D6	D5	D4	D3	D2	D1	D0	Action
Write Data Byte	1	0	#	#	#	#	#	#	#	#	Write 1 byte @ PA/CA
Read Data Byte	1	1	#	#	#	#	#	#	#	#	Read 1 byte @ PA/CA
Get Status	0	1	BZ	MX	DE	RS	0	0	0	0	Get Status Summary
Set Column Address LSB	0	0	0	0	0	0	#	#	#	#	Set CA[3:0]=D[3:0]
Set Column Address MSB	0	0	0	0	0	1	#	#	#	#	Set CA[7:4] =D[3:0]
Set Mux rate & Gain Parameter. ¹⁾	0	0	0	0	1	0	0	#	#	#	Set MR=D[2] Set GN[1:0]=D[1:0]
Set Mux rate & Temperature Compensation. ²⁾	0	0	0	0	1	0	0	#	#	#	Set MR=D[2] Set TC[1:0]=D[1:0]
Set Power Control	0	0	0	0	1	0	1	#	#	#	Set PC[2:0]=D[2:0]
Set Adv. Program Control (double byte command)	0	0	0	0	1	1	0	0	R		Set APC[R][7:0]=D[7:0], where R = 00, or 01
	0	0	#	#	#	#	#	#	#	#	
Set Start Line	0	0	0	1	#	#	#	#	#	#	Set SL[5:0]=D[5:0]
Set V _{REF} potential meter (double-byte command) ¹⁾	0	0	1	0	0	0	0	0	0	1	Set PM[5:0]=D[5:0] Set TC[1:0]=D[7:6]
Set V _{REF} potential meter (double-byte command) ²⁾	0	0	1	0	0	0	0	0	0	1	Set PM[5:0]=D[5:0] Set GN[1:0]=D[7:6]
Set RAM Address Control	0	0	1	0	0	0	1	#	#	#	Set AC[2:0]=D[2:0]
Set Serial Bus Control	0	0	1	0	0	1	0	0	#	#	Set BC[1:0]=D[1:0]
Set Column Mirroring	0	0	1	0	1	0	0	0	0	#	Set LC[2]=D0
Set All-Pixel-ON	0	0	1	0	1	0	0	1	0	#	Set DC[1]=D0
Set Inverse Display	0	0	1	0	1	0	0	1	1	#	Set DC[0]=D0
Set Display ON/OFF	0	0	1	0	1	0	1	#	#	#	Set DC[4:2]=D[2:0]
Set Page Address	0	0	1	0	1	1	#	#	#	#	Set PA[3:0]=D[3:0]
Set LCD to RAM Mapping	0	0	1	1	0	0	#	#	#	#	Set LC[3:0]=D[3:0]
System Reset	0	0	1	1	1	0	0	0	1	0	System Reset sequence
NOP	0	0	1	1	1	0	0	0	1	1	No operation
Set LCD Bias Ratio	0	0	1	1	1	0	1	0	#	#	Set BR[1:0]= D[1:0]
Reset Cursor Update Mode	0	0	1	1	1	0	1	1	1	0	Set AC[3]=0, CA=CR;
Set Cursor Update Mode	0	0	1	1	1	0	1	1	1	1	Set AC[3]=1, CR=CA;
Set Test Control (double byte command)	0	0	1	1	1	0	0	1	TT		For testing only. Do not use.
	0	0	#	#	#	#	#	#	#	#	

7. Optical Characteristics

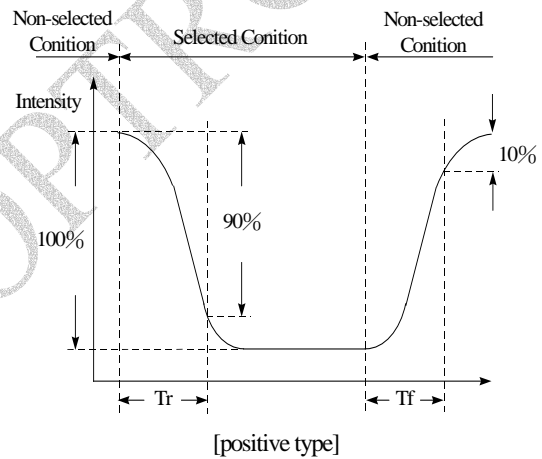
Ta=25°C

Item	Symbol	Condition	Min	Typ	Max	Unit
View Angle	(V) θ	CR \geq 2	30	—	60	deg
	(H) φ	CR \geq 2	-45	—	45	deg
Contrast Ratio	CR	—	—	5	—	—
Response Time	T rise	—	—	142	—	ms
	T fall	—	—	200	—	ms

Definition of Operation Voltage (Vop)



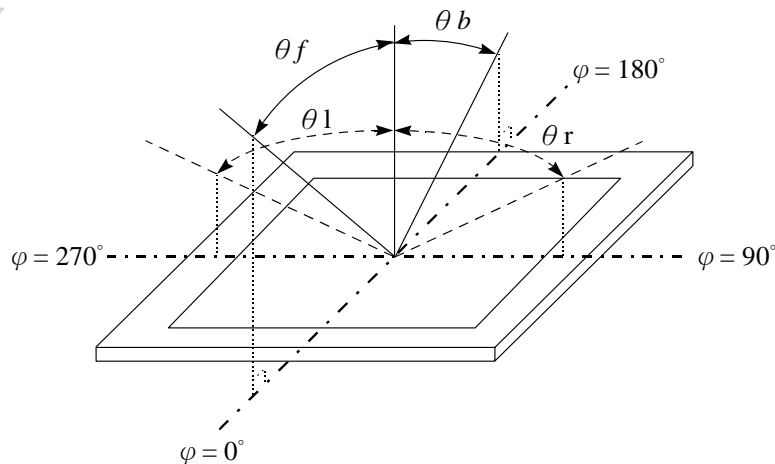
Definition of Response Time (Tr, Tf)



Conditions :

Operating Voltage : Vop Viewing Angle(θ , φ) : 0° , 0°
 Frame Frequency : 64 HZ Driving Waveform : 1/N duty , 1/a bias

Definition of viewing angle(CR \geq 2)



8. Absolute Maximum Ratings

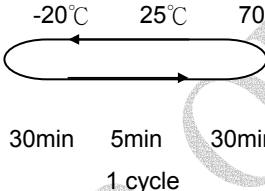
Item	Symbol	Min	Typ	Max	Unit
Operating Temperature	T_{OP}	-20	—	+70	°C
Storage Temperature	T_{ST}	-30	—	+80	°C
Input Voltage	V_{IN}/V_{OUT}	-0.3	—	$V_{DD}+0.3$	V
Supply Voltage For Logic	$V_{DD}-V_{SS}$	-0.3		4.0	V
LCD Driver Supply Voltage	V_{LCD}	-0.3		+17.0	V

9. Electrical Characteristics

Item	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage For Logic	$V_{DD}-V_{SS}$	—	2.7	2.8~3.3	3.6	V
Supply Voltage For LCM	V_{LCD}	$T_a=-20^{\circ}\text{C}$	14.7	15.0	15.3	V
		$T_a=25^{\circ}\text{C}$	15.2	15.5	15.8	V
		$T_a=70^{\circ}\text{C}$	15.4	15.7	16.0	V
Supply Current(No include LED Backlight)	I_{DD}	$V_{DD}=3.0\text{V}$		1.1		mA

10. Reliability

Content of Reliability Test (wide temperature, -20°C~70°C)

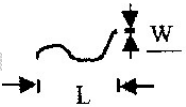
Environmental Test			
Test Item	Content of Test	Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the high storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	-
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity Operation	The module should be allowed to stand at 60°C,90%RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	<p>The sample should be allowed stand the following 10 cycles of operation</p>  <p style="text-align: center;">-20°C 25°C 70°C</p> <p style="text-align: center;">30min 5min 30min</p> <p style="text-align: center;">1 cycle</p>	-20°C/70°C 10 cycles	-
Vibration test	Endurance test applying the vibration during transportation and using.	fixed amplitude: 15mm Vibration. Frequency: 10~55Hz. One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5kΩ CS=100pF 1 time	—

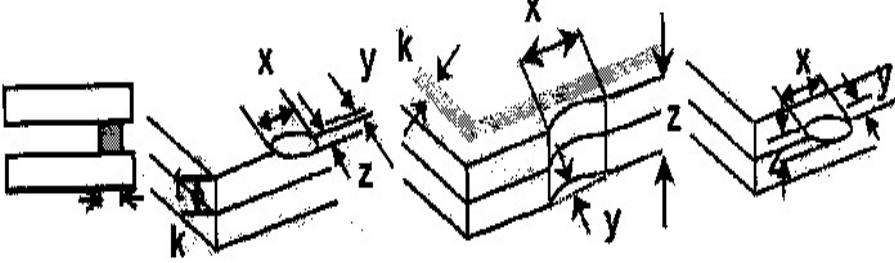
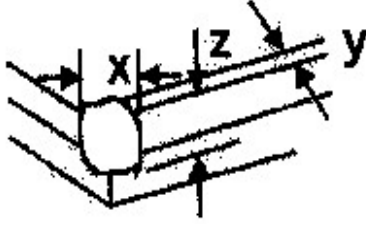
Note1: No dew condensation to be observed.

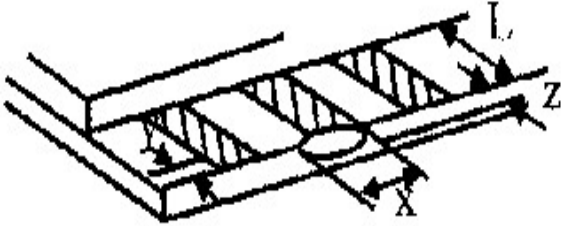
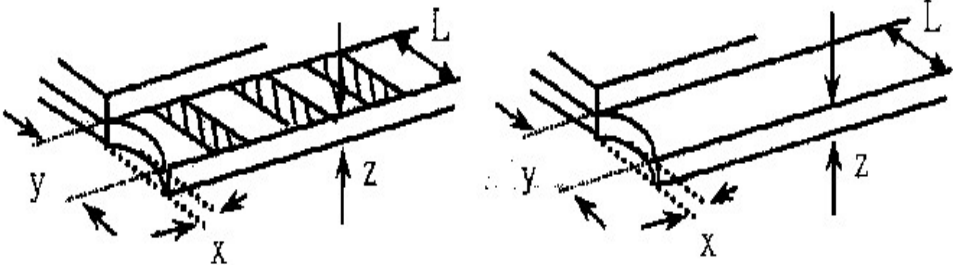
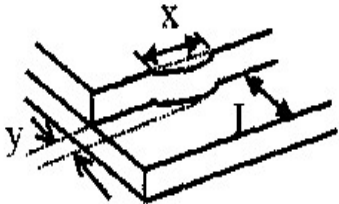
Note2: The function test shall be conducted after 4 hours storage at the normal temperature and humidity after remove from the test chamber.

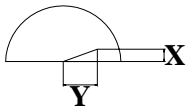
Note3: The packing have to including into the vibration testing..

11. Inspection specification

NO	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Contrast defect.	0.65												
02	Black or white spots on LCD (display only)	2.1 White and black spots on display $\leq 0.25\text{mm}$, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm	2.5												
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type : As following drawing $\Phi = (x + y) / 2$	2.5												
		3.2 Line type : (As following drawing)  <table border="1"> <thead> <tr> <th>Length</th> <th>Width</th> <th>Acceptable QTY</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> </tr> <tr> <td>$L \leq 3.0$</td> <td>$0.02 < W \leq 0.03$</td> <td rowspan="2">2</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.05$</td> </tr> <tr> <td>---</td> <td>$0.05 < W$</td> <td>As round type</td> </tr> </tbody> </table>	Length	Width	Acceptable QTY	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.03$	2	$L \leq 2.5$	$0.03 < W \leq 0.05$	---	$0.05 < W$
Length	Width	Acceptable QTY													
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$L \leq 3.0$	$0.02 < W \leq 0.03$	2													
$L \leq 2.5$	$0.03 < W \leq 0.05$														
---	$0.05 < W$	As round type													
04	Polarizer bubbles	If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction. <table border="1"> <thead> <tr> <th>Size Φ</th> <th>Acceptable QTY</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.20$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.50$</td> <td>3</td> </tr> <tr> <td>$0.50 < \Phi \leq 1.00$</td> <td>2</td> </tr> <tr> <td>$1.00 < \Phi$</td> <td>0</td> </tr> <tr> <td>Total QTY</td> <td>3</td> </tr> </tbody> </table>	Size Φ	Acceptable QTY	$\Phi \leq 0.20$	Accept no dense	$0.20 < \Phi \leq 0.50$	3	$0.50 < \Phi \leq 1.00$	2	$1.00 < \Phi$	0	Total QTY	3	2.5
Size Φ	Acceptable QTY														
$\Phi \leq 0.20$	Accept no dense														
$0.20 < \Phi \leq 0.50$	3														
$0.50 < \Phi \leq 1.00$	2														
$1.00 < \Phi$	0														
Total QTY	3														

NO	Item	Criterion	AQL																		
05	Scratches	Follow NO.3 LCD black spots, white spots, contamination																			
06	Chipped glass	<p>Symbols Define: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length:</p> <p>6.1 General glass chip : 6.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="443 1077 1358 1234"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙ If there are 2 or more chips, x is total length of each chip.</p> <p>6.1.2 Corner crack:</p>  <table border="1" data-bbox="443 1615 1358 1771"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙ If there are 2 or more chips, x is the total length of each chip.</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			
z: Chip thickness	y: Chip width	x: Chip length																			
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$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$																			

NO	Item	Criterion	AQL																
06	Glass crack	<p>Symbols :</p> <p>x: Chip length y: Chip width z: Chip thickness</p> <p>k: Seal width t: Glass thickness a: LCD side length</p> <p>L: Electrode pad length</p> <p>6.2 Protrusion over terminal :</p> <p>6.2.1 Chip on electrode pad :</p>  <table border="1" data-bbox="336 896 1262 981"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>6.2.2 Non-conductive portion:</p>  <table border="1" data-bbox="410 1305 1262 1424"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications.</p> <p>⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged.</p> <p>6.2.3 Substrate protuberance and internal crack.</p>  <table border="1" data-bbox="746 1668 1262 1753"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$x \leq a$</td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$x \leq a$	2.5
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$x \leq a$																		

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
08	Backlight elements	8.1 Illumination source flickers when lit. 8.2 Spots or scratched that appear when lit must be judged. Using LCD spot, lines and contamination standards. 8.3 Backlight doesn't light or color wrong.	0.65 2.5 0.65
09	Bezel	9.1 Bezel may not have rust, be deformed or have fingerprints, stains or other contamination. 9.2 Bezel must comply with job specifications.	2.5 0.65
10	PCB · COB	10.1 COB seal may not have pinholes larger than 0.2mm or contamination. 10.2 COB seal surface may not have pinholes through to the IC. 10.3 The height of the COB should not exceed the height indicated in the assembly diagram. 10.4 There may not be more than 2mm of sealant outside the seal area on the PCB. And there should be no more than three places. 10.5 No oxidation or contamination PCB terminals. 10.6 Parts on PCB must be the same as on the production characteristic chart. There should be no wrong parts, missing parts or excess parts. 10.7 The jumper on the PCB should conform to the product characteristic chart. 10.8 If solder gets on bezel tab pads, LED pad, zebra pad or screw hold pad, make sure it is smoothed down. 10.9 The Scraping testing standard for Copper Coating of PCB  $X * Y \leq 2\text{mm}^2$	2.5 2.5 0.65 2.5 2.5 0.65 0.65 2.5 2.5
11	Soldering	11.1 No un-melted solder paste may be present on the PCB. 11.2 No cold solder joints, missing solder connections, oxidation or icicle. 11.3 No residue or solder balls on PCB. 11.4 No short circuits in components on PCB.	2.5 2.5 2.5 0.65

NO	Item	Criterion	AQL
12	General appearance	12.1 No oxidation, contamination, curves or, bends on interface Pin (OLB) of TCP.	2.5
		12.2 No cracks on interface pin (OLB) of TCP.	0.65
		12.3 No contamination, solder residue or solder balls on product.	2.5
		12.4 The IC on the TCP may not be damaged, circuits.	2.5
		12.5 The uppermost edge of the protective strip on the interface pin must be present or look as if it causes the interface pin to sever.	2.5
		12.6 The residual rosin or tin oil of soldering (component or chip component) is not burned into brown or black color.	2.5
		12.7 Sealant on top of the ITO circuit has not hardened.	0.65
		12.8 Pin type must match type in specification sheet.	0.65
		12.9 LCD pin loose or missing pins.	0.65
		12.10 Product packaging must the same as specified on packaging specification sheet.	0.65
		12.11 Product dimension and structure must conform to product specification sheet.	0.65

12. Precautions in use of LCD Modules

1. Avoid applying excessive shocks to the module or making any alterations or modifications to it.
2. Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
3. Don't disassemble the LCM.
4. Don't operate it above the absolute maximum rating.
5. Don't drop, bend or twist LCM.
6. Soldering: only to the I/O terminals.
7. Storage: please storage in anti-static electricity container and clean environment.
8. Raystar have the right to change the passive components
(Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
9. Raystar have the right to change the PCB Rev.

13. Material List of Components for RoHs

1. RAYSTAR Optronics Co., Ltd. hereby declares that all of or part of products, including, but not limited to, the LCM, accessories or packages, manufactured and/or delivered to your company (including your subsidiaries and affiliated company) directly or indirectly by our company (including our subsidiaries or affiliated companies) do not intentionally contain any of the substances listed in all applicable EU directives and regulations, including the following substances.

Exhibit A : The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm
Above limited value is set up according to RoHS.						

2. Process for RoHS requirement :

- (1) Use the Sn/Ag/Cu soldering surface ; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :
 Reflow : 250°C , 30 seconds Max. ;
 Connector soldering wave or hand soldering : 320°C , 10 seconds max.
- (3) Temp. curve of reflow, max. Temp. : 235±5°C ;
 Recommended customer's soldering temp. of connector : 280°C , 3 seconds.

14. Recommendable storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module

LCM Sample Estimate Feedback Sheet

Module Number : _____

1 、 Panel Specification :

1. Panel Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. View Direction :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Numbers of Dots :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. View Area :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Active Area :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. Operating Temperature :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Storage Temperature :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8. Others :	_____	

2 、 Mechanical Specification :

1. PCB Size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Frame Size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Material of Frame :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Connector Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Fix Hole Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. Backlight Position :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Thickness of PCB :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8. Height of Frame to PCB :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
9. Height of Module :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
10. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

3 、 Relative Hole Size :

1. Pitch of Connector :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. Hole size of Connector :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. Mounting Hole size :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. Mounting Hole Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

4 、 Backlight Specification :

1. B/L Type :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2. B/L Color :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3. B/L Driving Voltage (Reference for LED Type) :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4. B/L Driving Current :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5. Brightness of B/L :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6. B/L Solder Method :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7. Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

>> Go to page 2 <<

Module Number : _____

5 、 Electronic Characteristics of Module :

1.Input Voltage :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
2.Supply Current :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
3.Driving Voltage for LCD :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
4.Contrast for LCD :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
5.B/L Driving Method :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
6.Negative Voltage Output :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
7.Interface Function :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
8.LCD Uniformity :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
9.ESD test :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____
10.Others :	<input type="checkbox"/> Pass	<input type="checkbox"/> NG , _____

6 、 Summary :

Sales signature : _____

Customer Signature : _____

Date : / /